

SECTION 27 05 26
GROUNDING AND BONDING FOR COMMUNICATIONS SYSTEMS

PART 1 - GENERAL

1.1 DESCRIPTION

- A. This section specifies general grounding and bonding requirements of telecommunication installations for equipment operations.
- B. "Grounding electrode system" refers to all electrodes required by NEC, as well as including made, supplementary, telecommunications system grounding electrodes.
- C. The terms "connect" and "bond" are used interchangeably in this specification and have the same meaning.

1.2 RELATED WORK

- A. Section 27 05 11, REQUIREMENTS FOR COMMUNICATIONS INSTALLATIONS: General electrical requirements and items that are common to more than one section of Division 27.
- B. Section 27 10 00, STRUCTURED CABLING: Low Voltage power and lighting wiring.

1.3 SUBMITTALS

- A. Submit in accordance with Section 27 05 11, REQUIREMENTS FOR COMMUNICATIONS INSTALLATIONS.
- B. Shop Drawings:
 - 1. Sufficient information, clearly presented, shall be included to determine compliance with drawings and specifications.
 - 2. Include the location of system grounding electrode connections and the routing of aboveground and underground grounding electrode conductors.
- C. Test Reports: Provide certified test reports of ground resistance.
- D. Certifications: Two weeks prior to final inspection, submit four copies of the following to the Resident Engineer:
 - 1. Certification that the materials and installation is in accordance with the drawings and specifications.
 - 2. Certification, by the Contractor, that the complete installation has been properly installed and tested.

1.4 APPLICABLE PUBLICATIONS

Publications listed below (including amendments, addenda, revisions, supplements, and errata) form a part of this specification to the extent referenced. Publications are referenced in the text by the basic designation only.

- A. American Society for Testing and Materials (ASTM):
 - B1-2001.....Standard Specification for Hard-Drawn Copper Wire
 - B8-2004.....Standard Specification for Concentric-Lay-Stranded Copper Conductors, Hard, Medium-Hard, or Soft
- B. Institute of Electrical and Electronics Engineers, Inc. (IEEE):
 - 81-1983.....IEEE Guide for Measuring Earth Resistivity, Ground Impedance, and Earth Surface Potentials of a Ground System
- C. National Fire Protection Association (NFPA):
 - 70-2005.....National Electrical Code (NEC)
- D. Telecommunications Industry Association, (TIA)
 - J-STO-607-A-2002.....Commercial Building Grounding (Earthing) and Bonding Requirements for Telecommunications
- E. Underwriters Laboratories, Inc. (UL):
 - 44-2005Thermoset-Insulated Wires and Cables
 - 83-2003Thermoplastic-Insulated Wires and Cables
 - 467-2004Grounding and Bonding Equipment
 - 486A-486B-2003Wire Connectors

PART 2 - PRODUCTS

2.1 GROUNDING AND BONDING CONDUCTORS

- A. Equipment grounding conductors shall be UL 83 insulated stranded copper, except that sizes 6 mm² (10 AWG) and smaller shall be solid copper. Insulation color shall be continuous green for all equipment grounding conductors, except that wire sizes 25 mm² (4 AWG) and larger shall be permitted to be identified per NEC.
- B. Bonding conductors shall be ASTM B8 bare stranded copper, except that sizes 6 mm² (10 AWG) and smaller shall be ASTM B1 solid bare copper wire.
- C. Isolated Power System: Type XHHW-2 insulation with a dielectric constant of 3.5 or less.
- D. Telecom System Grounding Riser Conductor: Telecommunications Grounding Riser shall be in accordance with J STO-607A. Use a minimum 50mm² (1/0 AWG) insulated stranded copper grounding conductor unless indicated otherwise.

2.2 SPLICES AND TERMINATION COMPONENTS

Components shall meet or exceed UL 467 and be clearly marked with the manufacturer, catalog number, and permitted conductor size(s).

PART 3 - EXECUTION

3.1 GENERAL

- A. Ground in accordance with the NEC, as shown on drawings, and as hereinafter specified.

3.2 TELECOMMUNICATIONS SYSTEM

- A. Bond telecommunications system grounding equipment to the electrical grounding electrode system.
- B. Furnish and install all wire and hardware required to properly ground, bond and connect communications raceway, cable tray, metallic cable shields, and equipment to a ground source.
- C. Ground bonding jumpers shall be continuous with no splices. Use the shortest length of bonding jumper possible.
- D. Provide ground paths that are permanent and continuous with a resistance of 1 ohm or less from raceway, cable tray, and equipment connections to the building grounding electrode. The resistance across individual bonding connections shall be 10 milli ohms or less.
- E. Below-Grade Grounding Connections: When making exothermic welds, wire brush or file the point of contact to a bare metal surface. Use exothermic welding cartridges and molds in accordance with the manufacturer's recommendations. After welds have been made and cooled, brush slag from the weld area and thoroughly cleaned the joint area. Notify the Resident Engineer prior to backfilling any ground connections.
- F. Above-Grade Grounding Connections: When making bolted or screwed connections to attach bonding jumpers, remove paint to expose the entire contact surface by grinding where necessary; thoroughly clean all connector, plate and other contact surfaces; and apply an appropriate corrosion inhibitor to all surfaces before joining.
- G. Bonding Jumpers:
 - 1. Use insulated ground wire of the size and type shown on the Drawings or use a minimum of 16 mm² (6 AWG) insulated copper wire.
 - 2. Assemble bonding jumpers using insulated ground wire terminated with compression connectors.

3. Use compression connectors of proper size for conductors specified. Use connector manufacturer's compression tool.

H. Bonding Jumper Fasteners:

1. Conduit: Fasten bonding jumpers using screw lugs on grounding bushings or conduit strut clamps, or the clamp pads on push-type conduit fasteners. When screw lug connection to a conduit strut clamp is not possible, fasten the plain end of a bonding jumper wire by slipping the plain end under the conduit strut clamp pad; tighten the clamp screw firmly. Where appropriate, use zinc-plated external tooth lockwashers.
2. Wireway and Cable Tray: Fasten bonding jumpers using zinc-plated bolts, external tooth lockwashers, and nuts. Install protective cover, e.g., zinc-plated acorn nuts on any bolts extending into wireway or cable tray to prevent cable damage.
3. Ground Plates and Busbars: Fasten bonding jumpers using two-hole compression lugs. Use tin-plated copper or copper alloy bolts, external tooth lockwashers, and nuts.
4. Unistrut and Raised Floor Stringers: Fasten bonding jumpers using zinc-plated, self-drill screws and external tooth lockwashers.

3.3 COMMUNICATIONS CABLE GROUNDING

- A. Bond all metallic cable sheaths in multipair communications cables together at each splicing and/or terminating location to provide 100 percent metallic sheath continuity throughout the communications distribution system.
 1. At terminal points, install a cable shield bonding connector provide a screw stud connection for ground wire. Use a bonding jumper to connect the cable shield connector to an appropriate ground source like the rack or cabinet ground bar.
 2. Bond all metallic cable shields together within splice closures using cable shield bonding connectors or the splice case grounding and bonding accessories provided by the splice case manufacturer. When an external ground connection is provided as part of splice closure, connect to an approved ground source and all other metallic components and equipment at that location.

3.4 COMMUNICATIONS RACEWAY GROUNDING

- A. Conduit: Use insulated 16 mm² (6 AWG) bonding jumpers to ground metallic conduit at each end and to bond at all intermediate metallic enclosures.

- B. Wireway: use insulated 16 mm² (6 AWG) bonding jumpers to ground or bond metallic wireway at each end at all intermediate metallic enclosures and across all section junctions.
- C. Cable Tray Systems: Use insulated 16 mm² (6 AWG) bonding jumpers to ground cable tray to column-mounted building ground plates (pads) at each end and approximately every 16 meters (50 feet).

3.5 GROUND RESISTANCE

- A. Grounding system resistance to ground shall not exceed 5 ohms. Make necessary modifications or additions to the grounding electrode system for compliance without additional cost to the Government. Final tests shall assure that this requirement is met.
- B. Resistance of the grounding electrode system shall be measured using a four-terminal fall-of-potential method as defined in IEEE 81. Ground resistance measurements shall be made before the electrical distribution system is energized and shall be made in normally dry conditions not less than 48 hours after the last rainfall. Resistance measurements of separate grounding electrode systems shall be made before the systems are bonded together below grade. The combined resistance of separate systems may be used to meet the required resistance, but the specified number of electrodes must still be provided.
- C. Services at power company interface points shall comply with the power company ground resistance requirements.
- D. Below-grade connections shall be visually inspected by the Resident Engineer prior to backfilling. The Contractor shall notify the Resident Engineer 24 hours before the connections are ready for inspection.

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